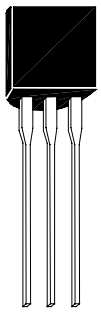
HE8550S

PNP EPITAXIAL PLANAR TRANSISTOR



TO-92

Description

The HE8550S is designed for general purpose amplifier applications.

Features

- High DC Current gain: 100-500 at IC=150mA
- Complementary to HE8050S

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -25 V
  VCEO Collector to Emitter Voltage ..... -20 V
  VEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -700 mA

Characteristics (Ta=25°C)

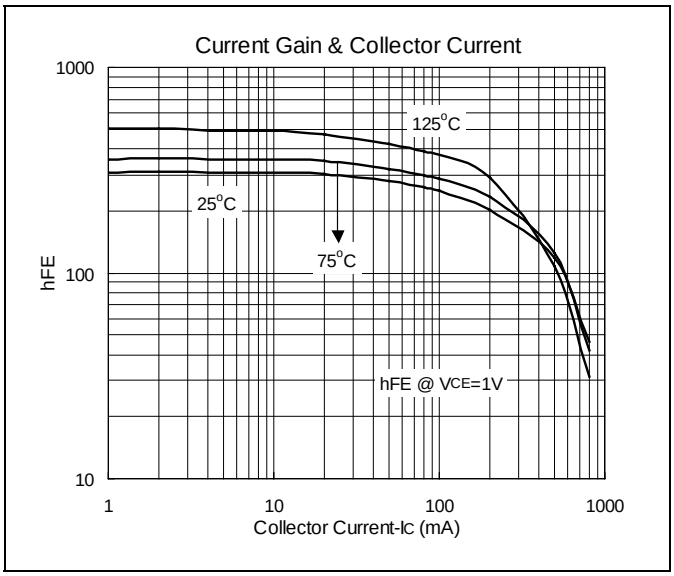
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-25	-	-	V	IC=-10uA, IE=0
BVCEO	-20	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-20V, IE=0
*VCE(sat)	-	-	-0.5	V	IC=-0.5A, IB=-50mA
VBE(on)	-	-	-1	V	VCE=-1V, IC=-150mA
*hFE1	100	-	500		VCE=-1V, IC=-150mA
*hFE2	-	100	-		VCE=-1V, IC=-500mA
fT	150	-	-	MHz	VCE=-10V, IC=-20mA, f=100MHz
Cob	-	-	10	pF	VCB=-10V, f=1MHz

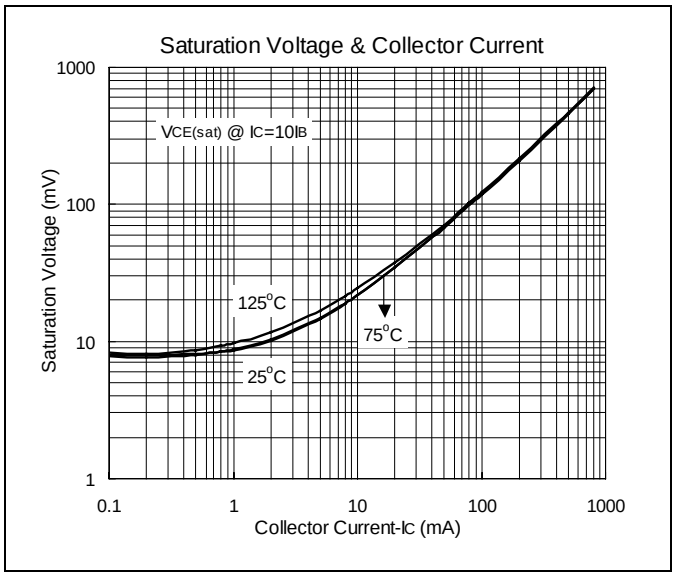
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

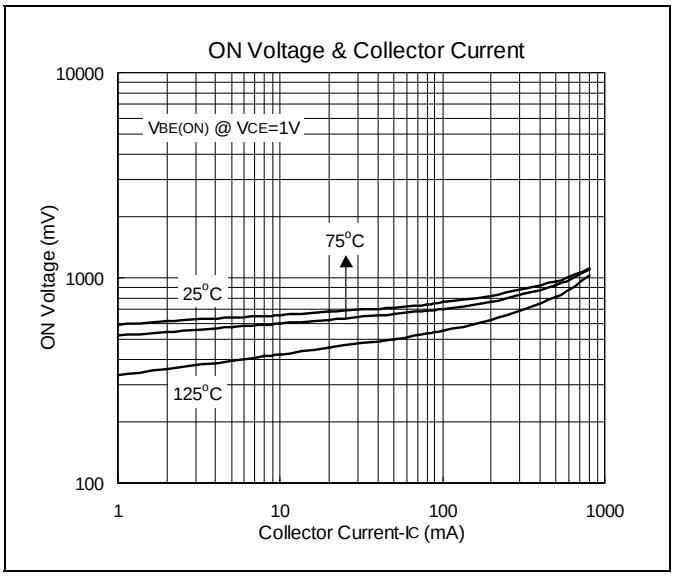
Classification Of hEF

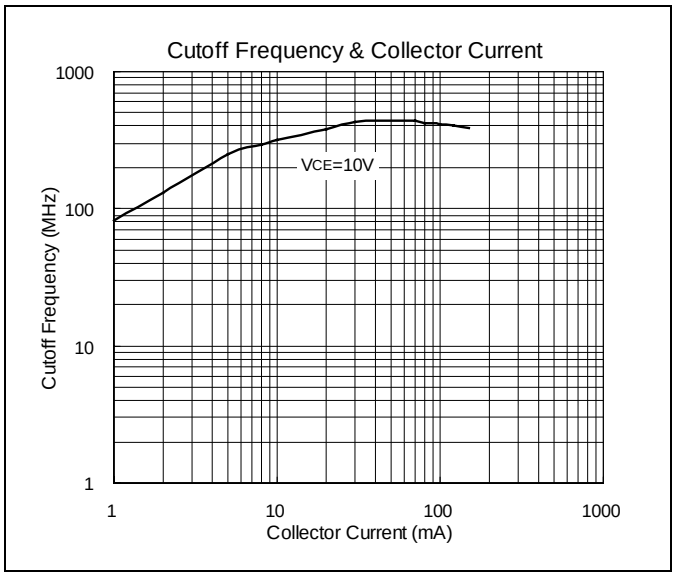
Rank	C	C1	D	D1	E
hFE1	100-180	100-180	160-300	160-300	250-500
hFE2	-	>100	-	>100	-

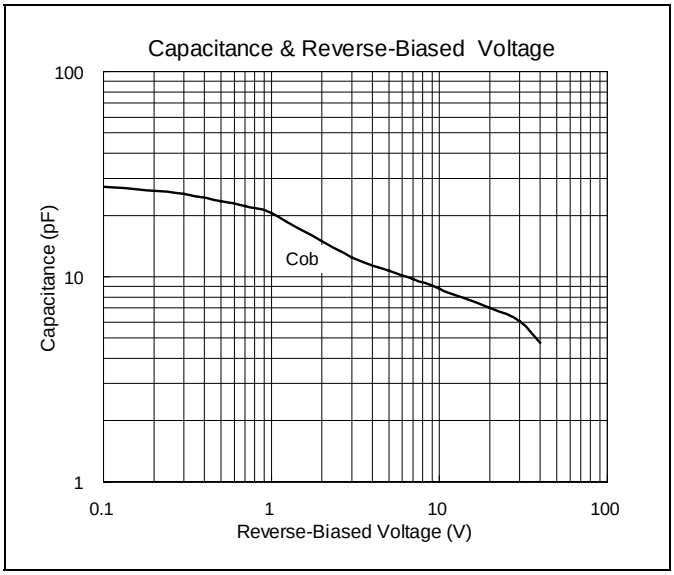
Characteristics Curve

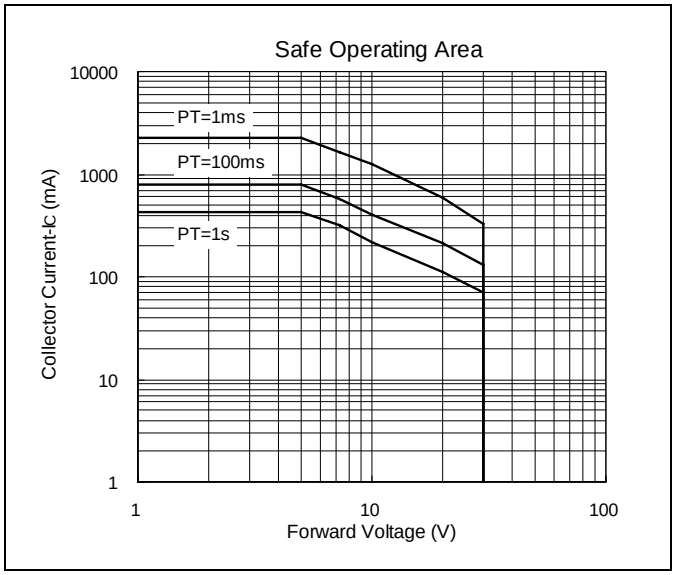


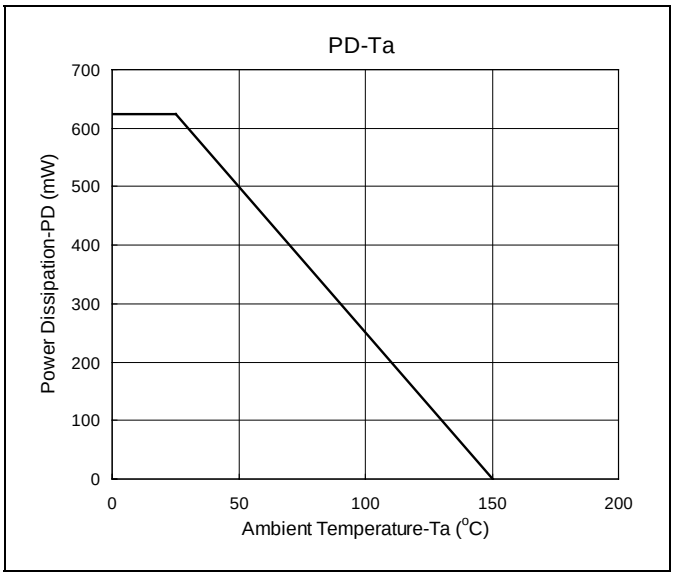




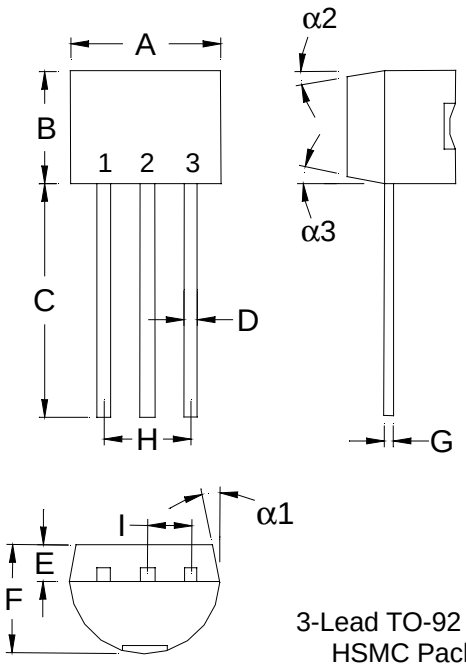






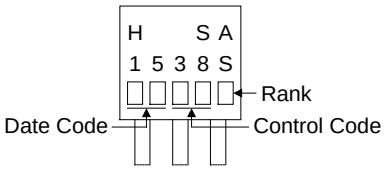

PD-Ta
Power Dissipation-PD (mW)
700
600
500
400
300
200
100
0
0
50
100
150
200
Ambient Temperature-Ta (°C)

TO-92 Dimension



3-Lead TO-92 Plastic Package
HSMC Package Code: A

Marking:



Style: Pin 1.Emitter 2.Collector 3.Base

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Head Office And Factory:

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- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
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